

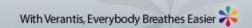
Semiconductor chip manufacturing utilizes a variety of inorganic acids and ammonia solutions. Mixing of acid gases and ammonia in a ventilation system can result in a gas phase reaction producing very fine particulate that is difficult and expensive to remove. For this reason a large semiconductor foundry on the west coast decided to pre-treat the exhaust from the ammonia sources prior to mixing with the general ventilation from the acid sources. The volume at each source was relatively small (1,500 – 2,500 CFM) and the customer's preference was to treat each source independently to avoid an elaborate duct arrangement.

Verantis had the perfect solution, our packaged Mini-Scrubber. The polypropylene units are designed as a complete compact assembly with support frame, top mounted fan, and automated controls. The unique sprayer design eliminates the need for a recirculation pump and piping reducing both energy usage and maintenance requirements. Using dilute sulfuric solution, the system is able to achieve > 95% ammonia removal.

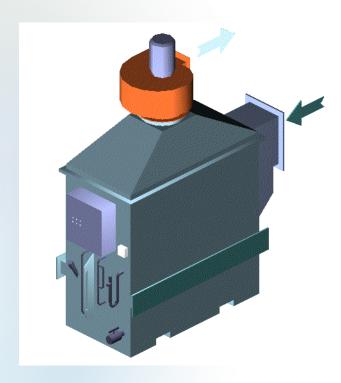
Product Literature: (click on links to take you to the literature)

**MS Product Data Sheet** 

**MS-II Product Data Sheet** 



## Ammonia Scrubbing in Semiconductor Manufacturing



Application	Wafer Fabrication Process Ventilation
Exhaust Volume	2,500 ACFM
Exhaust Temperature	Ambient
Contaminant	Ammonia
Removal Efficiency	95%
Scrubbing Solution	Dilute H <sub>2</sub> SO <sub>4</sub>
Exhaust Pressure	5″W.C.
Materials of Construction	Polypropylene



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